

Improved Wire Bond Package and Packaging Method**ABSTRACT**

5 A method for packaging a plurality of dies is disclosed. Each die is attached to
a corresponding mounting station in a structural member that includes a base member having
first and second surfaces and a plurality of mounting stations. Each mounting station has a
cavity wall that surrounds that mounting station and extends from the first surface thereby
forming an open cavity around the mounting station. After the dies have mounted, a lid sheet
10 is positioned over the structural member. The lid sheet includes a plurality of covers for
closing the cavities. The covers are connected to one another by connection members. The
structural member with the positioned lid sheet is then placed in a mold with a molding
compound in contact with the lid sheet. The mold has a surface that forces the covers against
the cavity while forcing the molding compound between the cavity walls.